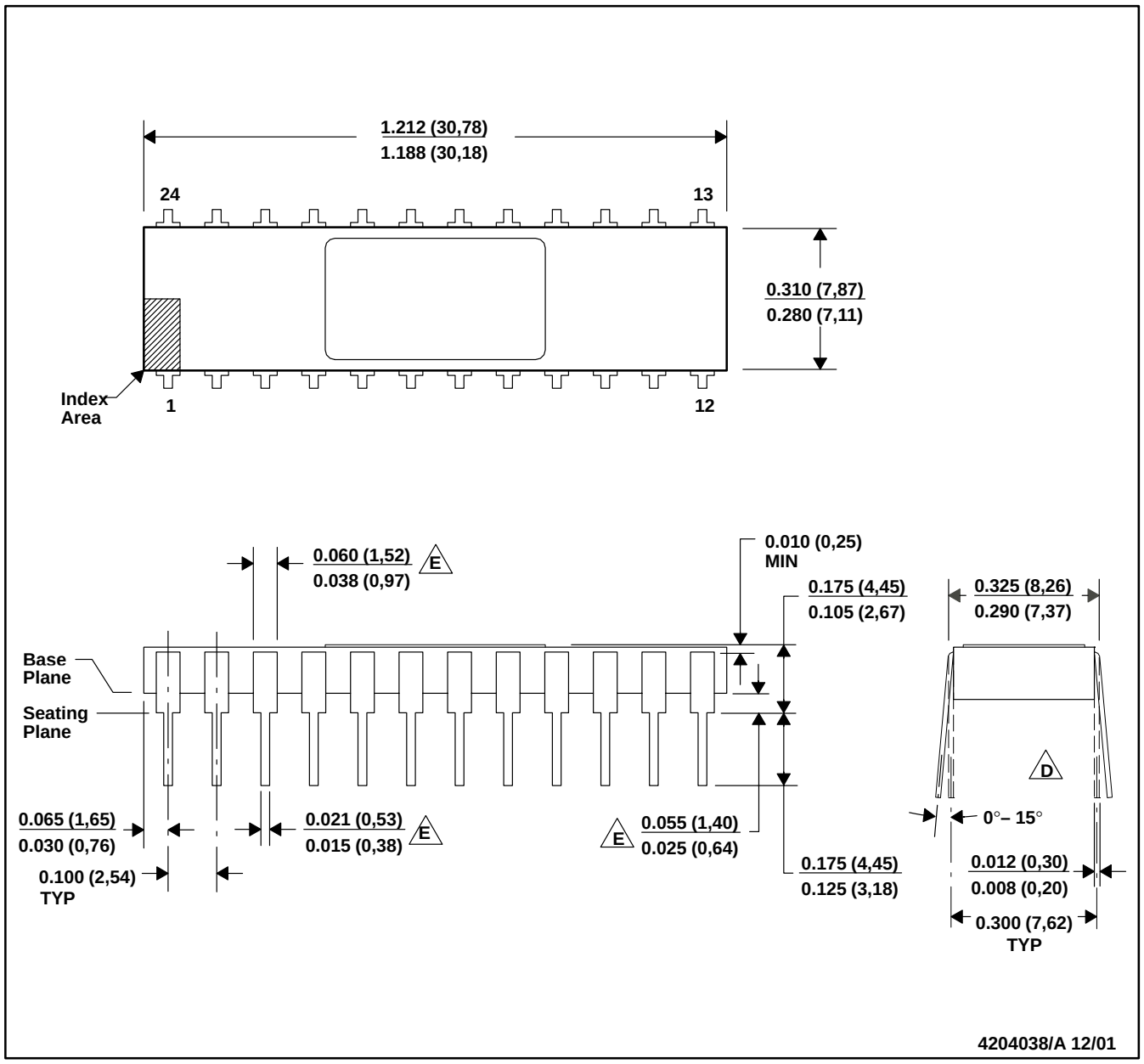
MCDI046 – JANUARY 2002

JDN (R–CDIP–T24) **CERAMIC SIDE-BRAZE DUAL-IN-LINE**



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Leads within 0.005 (0.13) radius of true position (TP) at gage plane with maximum material condition and unit installed.
D. The Package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
E. Outlines on which the seating plane is coincident with the plane (standoff = 0), terminal lead standoffs are not required, and lead shoulder may equal lead width along any part of the lead above the seating/base plane.
F. A visual index feature must be located within the cross-hatched area.

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